

ABSTRACT OF THE DISCLOSURE

A board for printed wiring comprises an electromagnetic wave absorbing laminate (EM) provided on a surface of a substrate (1) with the intervention of an adhesive layer (2) of a metal oxide, the
5 electromagnetic wave absorbing laminate (EM) comprising:
(a) a magnetic layer (3) comprising a plurality of magnetic particles (31) having an average particle diameter of 1 to 150 nm and isolated from each other by an electrically
10 insulative material (32); and (b) an electrically insulative layer (4), being alternately stacked in a multi-layer structure, the board for printed wiring has a reduced thickness and an improved electromagnetic wave absorbing characteristic in a high frequency band of not
15 lower than gigahertz, as compared with a conventional one which has an electromagnetic wave absorbing layer of a composite material including fine magnetic particles simply dispersed in a resin binder.